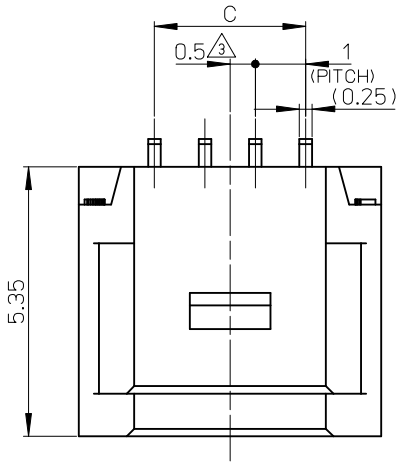
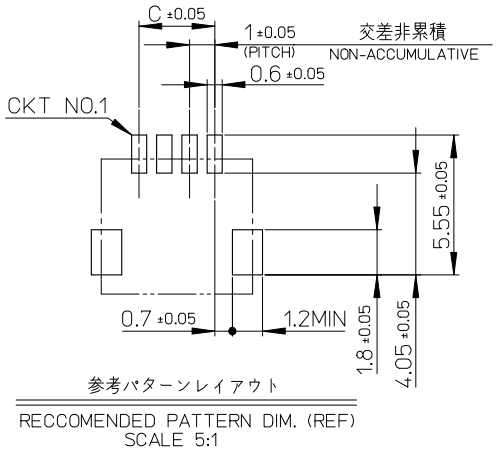
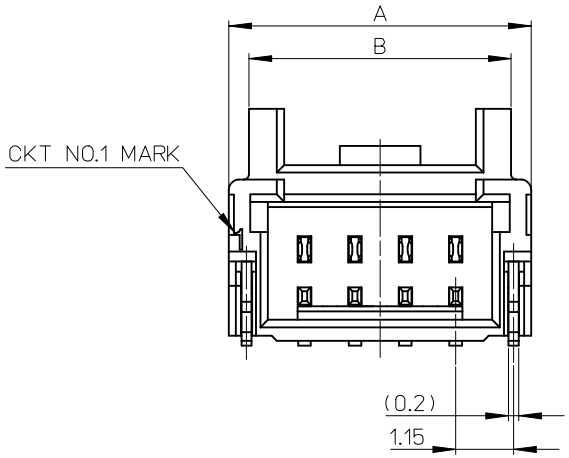
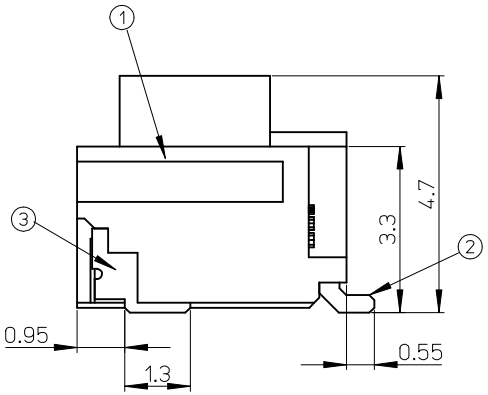
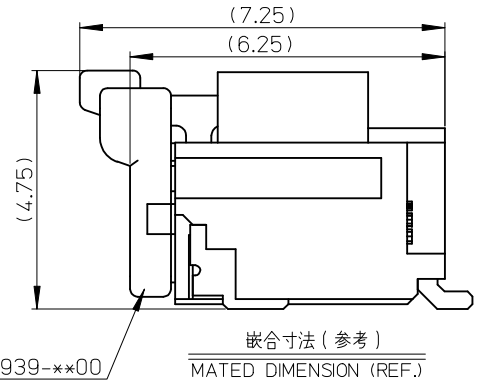




参考パターンレイアウト
RECCOMENDED PATTERN DIM. (REF)
SCALE 5:1







嵌合寸法（参考）
MATED DIMENSION (REF.)

番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色：表参照 Ⓔ HEAT RESISTANCE NYLON ,COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ：1.0μmMIN. TIN ニッケルメッキ（下地）：1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ：1.0μmMIN. TIN ニッケルメッキ（下地）：1.0μmMIN. NICKEL(UNDER PLATING)

NOTES.

1．嵌合相手：501939-****
MATE WITH：501939-****

2．ソルダーピン及びネイル平坦度は、0．1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.

△3 極数＝偶数に適用
APPLY FOR CKT SIZE=EVEN

4.ELV AND RoHS COMPLIANT.

4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

CONNECTOR SERIES No. 501953-***9

REVISED
EC NO: J2010-0339 2009/09/01
DRWN:TNAKAGAWA01 2009/09/01
CH'KD:HMATSUMOTO 2009/09/01
APPR:HHIRATA 2009/09/01
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 10:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	NYOSHIDA
DATE	2005/09/16
CHECKED BY	AMIZUMURA
DATE	2005/09/16
APPROVED BY	MYAGI
DATE	2005/09/16
MATERIAL NO.	SEE SHEET 2

TITLE
1.0 WIRE TO BOARD CONN.
WAFER ASS'Y 1-ROW R/A
POSI-LOCK

MOLEX INCORPORATED

DOCUMENT NO. SD-501953-001
SHEET NO. 1 OF 2

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
501953-0597	501953-0587	501953-0577	501953-0567	5
501953-0497	501953-0487	501953-0477	501953-0467	4
501953-0397	501953-0387	501953-0377	501953-0367	3
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数 CIRCUITS
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	

CONNECTOR SERIES No. 501953-***9

青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数 CIRCUITS
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	

CONNECTOR SERIES No. 501953-***9

REVISED
EC NO: J2010-0339
DRWN:TNAKAGAWA01 2009/09/01
CH'KD:HMATSUMOTO 2009/09/01
APPR:HHIRATA 2009/09/01
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±---
10 OVER 30 UNDER	±---
30 OVER	±---
ANGULAR	±--- °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2005/09/16
CHECKED BY: AMIZUMURA DATE: 2005/09/16
APPROVED BY: MYAGI DATE: 2005/09/16

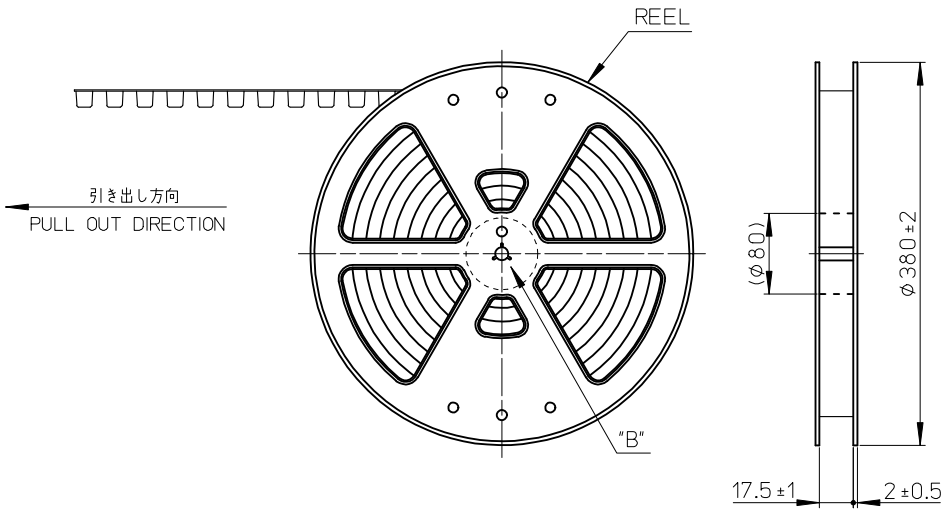
TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-501953-001
SHEET NO.: 2 OF 2
SIZE: A3

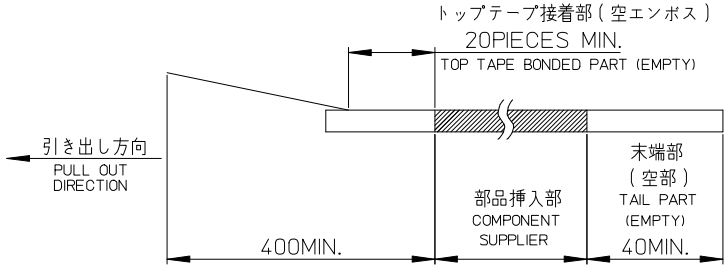
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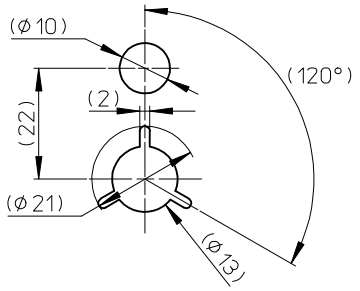


NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
   FOR DETAIL OF CONNECTOR DIMENSIONS,PLEASE SEE THE DRAWING OF CONNECTOR ITSELF(NOT PACKAGED).
2. 梱包数量：1300個／リール
   NUMBER OF CONNECTORS : 1300PIECES/REEL
3. リードテープ長さ
   LEAD TAPE LENGTH



4. 材料
   MATERIAL
   キャリアテープ：ポリスチレン
   CARRIER TAPE : POLYSTYRENE
   トップテープ：PET、その他
   TOP TAPE:PET,OTHER
   リール：ポリスチレン<リサイクル材を含む>
   REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
5. ELV AND RoHS COMPLIANT.
6. ハイバリア梱包（シリカゲル入り）対応品である。(501953-**07除く)
   THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
   (BESIDES 501953-**07)
7. 開梱後の保管条件に注意のこと。（ハイバリア品対象：PS-501940-001参照）
   REFER TO PS-501940-001(HIGH BARRIER PRODUCT)
   FOR CONDITIONS AFTER OPEN.



DETAIL "B"

REVISED	EC NO:	DESCRIPTION	REV
DRWN:TNAKAGAWA01	J2010-0339	2009/09/01	G
CHKD:HMATSUMOTO		2009/09/01	
APPR:HHIRATA		2009/09/01	

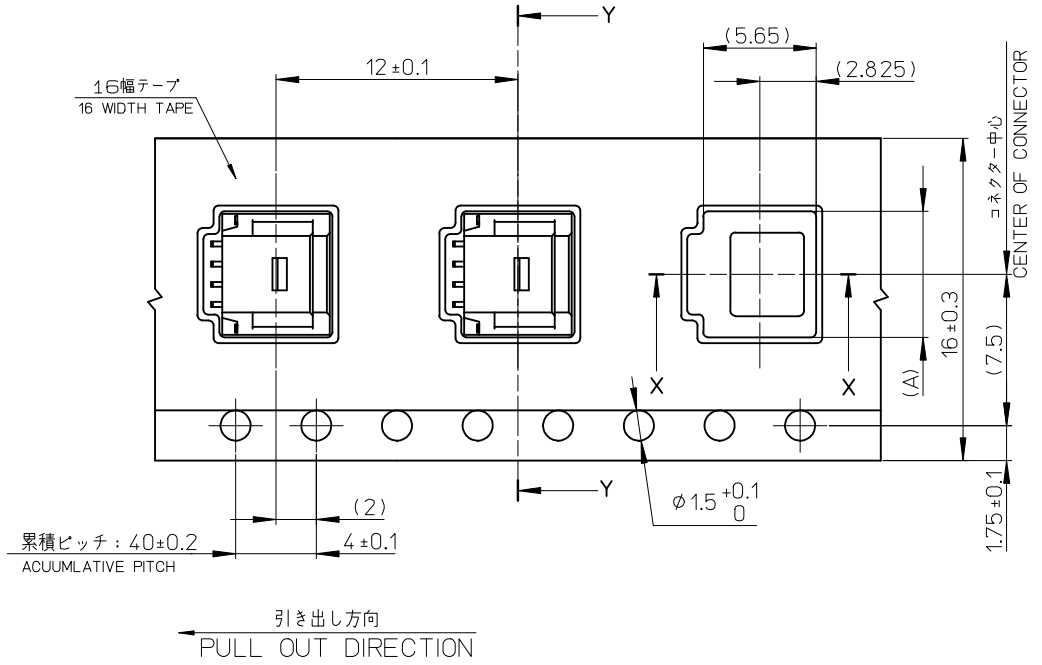
GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

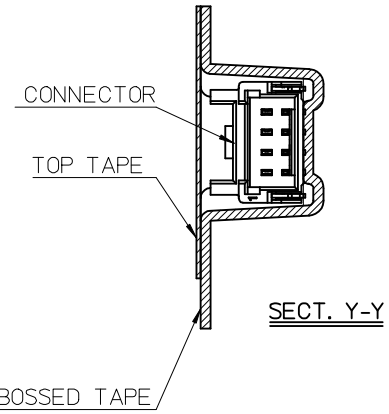
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

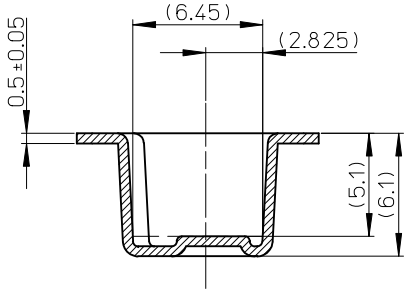
DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	NYOSHIDA 2005/09/16
CHECKED BY / DATE	AMIZUMURA 2005/09/16
APPROVED BY / DATE	MYAGI 2005/09/16
MATERIAL NO.	SEE SHEET 3
TITLE	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG
	MOLEX INCORPORATED
DOCUMENT NO.	SD-501953-002
SHEET NO.	1 OF 3
SIZE	A3

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7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-***9

REVISED
EC NO: J2010-0339 2009/09/01
DRWN:TNAKAGAWA01 2009/09/01
CH'KD:HMATSUMOTO 2009/09/01
APPR:HHIRATA 2009/09/01
DESCRIPTION
REV
G

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2005/09/16
CHECKED BY: AMIZUMURA DATE: 2005/09/16
APPROVED BY: MYAGI DATE: 2005/09/16

TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG

molex MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 3
DOCUMENT NO.: SD-501953-002
SHEET NO.: 2 OF 3
SIZE: A3

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紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
501953-0597	501953-0587	501953-0577	501953-0567	5
501953-0497	501953-0487	501953-0477	501953-0467	4
501953-0397	501953-0387	501953-0377	501953-0367	3
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数 CIRCUITS
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	

CONNECTOR SERIES No. 501953-***9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
501953-0547	501953-0537	501953-0527		501953-0507	5
501953-0447	501953-0437	501953-0427	501953-0417	501953-0407	4
501953-0347	501953-0337	501953-0327	501953-0317	501953-0307	3
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	極数 CIRCUITS
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	

CONNECTOR SERIES No. 501953-***9

REVISED
EC NO: J2010-0339 2009/09/01
DRWN:TNAKAGAWA01 2009/09/01
CH'KD:HMATSUMOTO 2009/09/01
APPR:HHIRATA 2009/09/01
DESCRIPTION
REV
G

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±---
10 OVER 30 UNDER	±---
30 OVER	±---
ANGULAR ±--- °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: NYOSHIDA DATE: 2005/09/16
CHECKED BY: AMIZUMURA DATE: 2005/09/16
APPROVED BY: MYAGI DATE: 2005/09/16

TITLE: 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-501953-002
SHEET NO.: 3 OF 3
SIZE: A3

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